

TECHNICAL REPORT

Functional materials

GX82K3

Die Attach Paste

1.Introduction

Die Attach Paste "GX82K3" is epoxy resin based and solvent free Type paste.
 The highest thermal conductivity (24.1W/mK)
 Good reflow performance due to lower moisture absorption resin system.
 GX82K3 is effectively used for power IC, transistor..

2.Features

- 1) Good workability for dispensing due to solvent free and one liquid type paste.
- 2) Highest thermal conductivity(24.1W/mK)

3. General Property

Properties		Unit	Typical Value	Test Method
Appearance		-	Silver Filled Paste	Visual
Viscosity at 25C		Pa·s	120	E-Type Viscometer 0.5rpm (3 ° cone)
Thixotropic Index		-	6.0	0.5rpm/5.0rpm
Non Volatile		wt%	82.0	180C×2hr
Silver Content		wt%	92	600C×3hr
Die shear strength	25C	Kgf	3.5	Frame : Cu/PPF Chip Size : 2x2mm
	300C		2.8	
Volume Resistivity		Ohm·cm	8×10^{-6}	Cure : 200C×90min. Measurement: Room Temp.
Glass Transition Temperature		C	160	TMA
Modules (25C)	25C	GPa	16.5	DMA
	260C		7.8	
CTE	Alpha1	Ppm	40	TMA
	Alpha2		125	
Ionic Impurity	Na	ppm	6	Atomic Absorption Ionchromatography
	Cl		1	
Thermal Conductivity		W/m K	24.1	Laser Flash

4. Standard Curing Condition

[1st Step] **165°C x120min** (Keeping time) in Oven

5. Remarks

Storage condition is -30 to -15°C

Asada Chemical

マニュアル操作を押してください